

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A non-sensitizing epoxy composition comprising:
an uncured epoxy resin composition including a non-sensitizing liquid epoxy resin and a non-sensitizing mercaptan composition capable of curing said epoxy resin when combined with said mercaptan composition to form a substantially uniform mixture, wherein said epoxy resin has a molecular weight of about 800-1000, said epoxy resin being admixed with fillers and colorants selected from the group consisting of talc, titanium dioxide, carbon black and mixtures thereof, wherein said epoxy composition has the consistency of a putty and is not a contact sensitizer.
2. (original) The composition as recited in claim 1, wherein said epoxy resin is about 20-30% by weight of said uncured epoxy resin composition.
- 3-4. (canceled)
5. (previously presented) The composition as recited in claim 1, wherein said epoxy resin has a molecular weight of from about 900-950.
6. (currently amended) The composition as recited in claim 1, wherein said liquid epoxy resin is a sorbitol glycidyl ether-aliphatic polyfunctional epoxy resin.
- 7-9. (canceled)
10. (currently amended) A method of forming a non-sensitizing epoxy putty composition, comprising:

combining an uncured epoxy resin composition including a non-sensitizing liquid epoxy resin and a non-sensitizing mercaptan composition capable of curing said epoxy resin when combined with said mercaptan composition to form a substantially uniform mixture, wherein said epoxy resin has a molecular weight of about 800-1000, said epoxy resin being admixed with fillers and colorants selected from the group consisting of talc,

titanium dioxide, carbon black and mixtures thereof, wherein said epoxy composition has the consistency of a putty and is not a contact sensitizer.

11. (original) The method as recited in claim 10, wherein said epoxy resin is about 20-30% by weight of said uncured epoxy resin composition.

12-13. (canceled)

14. (original) The method as recited in claim 10, wherein said epoxy resin has a molecular weight of from about 900-950.

15. (currently amended) The method as recited in claim 10, wherein said ~~liquid~~ epoxy resin is a sorbitol glycidyl ether-aliphatic polyfunctional epoxy resin.

16-17. (canceled)